

Exhibitor Statements Bondexpo 2009

UHU Vertrieb GmbH

UHU has been exhibiting at BONDexpo for three years now – right from the very beginning. Of course our trade fair leads still have to be evaluated individually, but our first impression indicates that the quantity as well as the quality of our leads can be ranked as good to very good. We hold BONDexpo in high regard as a platform for our product offerings. This year we're presenting a special range of PVC adhesives as a new product. This has provided us with an additional highlight for our trade fair booth, and has drawn the attention of the customers to the extent of our industrial product range to an even greater degree. We feel it's important to further expand BONDexpo, especially in light of the fact that there aren't any other comparable trade fairs in Germany. Without a doubt, bonding will be an important joining and fastening technique in the future. It offers numerous advantages as opposed to other technologies: It reduces the number of work steps, it's flexible where handling is concerned, and it can be used in a wide variety of applications.

Stefan Hilbrath, trade division manager for industrial and commercial technology, UHU Vertrieb GmbH, Bühl, Germany

Diener electronic

We're very, very satisfied with this year's BONDexpo – despite the omnipresent crisis debate. Our contacts were very good, in terms of both quantity and quality. The visitors were primarily specialists, and the way things look at the moment the trade fair went at least as well as last year's BONDexpo. We'd nevertheless like to be able to reach a more international public at BONDexpo. We offer a broad spectrum of products, and exhibit at 12 to 13 trade fairs each year in Germany alone. For us, BONDexpo ranks amongst the five most important German trade fairs.

Ing. Daniela Schubert, process development, Diener electronic GmbH + Co. KG, Nagold, Germany

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REIS GmbH & Co. KG

Our focal points at BONDexpo 2009 included the topics of sealing and bonding with the help of robots. After experiencing a somewhat sluggish first day at the trade fair, things picked up on the following day and the last day of the event was especially productive this year. We hardly have any visitors at BONDexpo who are just looking around – on the contrary, we get very targeted RFQs and have well founded discussions.

Dipl.-Ing. Michael Knaf, division manager for bonding and plastics automation, REIS GmbH & Co. KG Maschinenfabrik, Obernburg, Germany

tewipack Uhl GmbH – klebetechnik

We looked upon our participation at the trade fair as an experiment during these tough economic times, but we got off to a good start right from the beginning on Monday. Tuesday and Wednesday were outstanding. We have the feeling that the quality of the visitors has once again increased as compared with previous years, and we were also very satisfied with visitor numbers. We consider the new theme parks and the congress a definite plus for the event. BONDexpo is a fixed item in our trade fair budget, because it's a perfect fit for us with regard to reaching our target group. We process the southern German market from here. All in all we'd say, keep up the good work, because BONDexpo is the world's only trade fair for industrial bonding technology.

Alexander Uhl, managing director, tewipack Uhl GmbH - klebetechnik, Althengstett, Germany

ARCOTEC GmbH

Already on the afternoon of the first day of the trade fair, we recorded heavy visitor traffic. We had to increase booth personnel on the following days, in order to be able to provide all interested parties with comprehensive consultation. The talk delivered by our Dr. Werner Eckert was very well received. We feel that in the meantime, bonding can be seen as a real alternative in many joining technology applications. The quality of the expert visitors was great. Lots of visitors came with concrete applications, for which we'll mutually develop the ideal solution.

Dipl.-Ing. Kai Harnisch, ARCOTEC GmbH, Mönshheim, Germany